

L Number	Hits	Search Text	DB	Time stamp
10	2	(US-20020074381-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:16
11	2	((US-20020074381-\$).did.) and (in or indium)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 12:52
12	14	((("6087021" or ("5812925" or ("4325734" or ("5621607" or ("3602979" or ("4614296" or ("6520401" or ("6187450" or ("5392982" or ("5542602" or ("6199751" or ("6340113" or ("5009360" or ("5025304")).PN.	USPAT	2003/09/16 12:53
13	10	((("6087021" or ("5812925" or ("4325734" or ("5621607" or ("3602979" or ("4614296" or ("6520401" or ("6187450" or ("5392982" or ("5542602" or ("6199751" or ("6340113" or ("5009360" or ("5025304")).PN.) and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:16
14	10	(US-6340113-\$ or US-6199751-\$ or US-6087021-\$ or US-5812925-\$ or US-5621607-\$ or US-5542602-\$ or US-5392982-\$ or US-5025304-\$ or US-5009360-\$ or US-4325734-\$).did.	USPAT	2003/09/16 12:55
15	9	((US-6340113-\$ or US-6199751-\$ or US-6087021-\$ or US-5812925-\$ or US-5621607-\$ or US-5542602-\$ or US-5392982-\$ or US-5025304-\$ or US-5009360-\$ or US-4325734-\$).did.) and (below or lower or less) with (melt or melting or liqu\$9) with (point or points or temperature or temperatures)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23
16	4	(US-5009360-\$ or US-5621607-\$ or US-5812925-\$ or US-4325734-\$).did.	USPAT	2003/09/16 13:03
17	4	((US-5009360-\$ or US-5621607-\$ or US-5812925-\$ or US-4325734-\$).did.) and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:16
18	1247	228/193-195.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:16
19	111	228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:22
20	80	228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23

21	119	(228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23
22	64	((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9))) and (below or lower or less) with (melt or melting or liqu\$9) with (point or points or temperature or temperatures)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:23
23	119	((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9))) or (((228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (bond\$9 or join\$9)) or (228/193-195.ccls. and (electronic or electronics or chip or chips or pcb or pcbs or circuit or circuits or semiconductor or semiconductors or optic or optics or optical) with (diffus\$9 or weld\$9 or braz\$9 or solder\$9))) and (below or lower or less) with (melt or melting or liqu\$9) with (point or points or temperature or temperatures))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/16 13:24